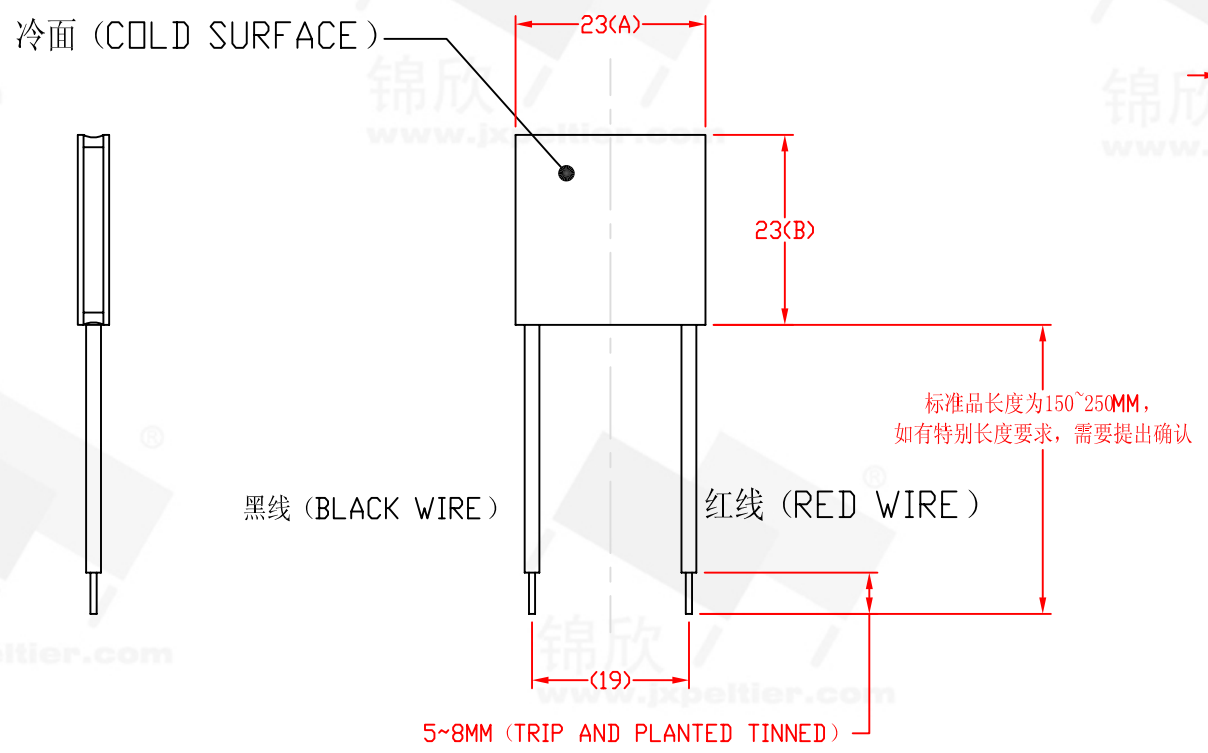


REVISIONS						
REV.	POS.	DESCRIPTION	DATE	DRW	APP	ECN#
A		INITIAL CREATION	2008/03/12	GARY	JUNSON	



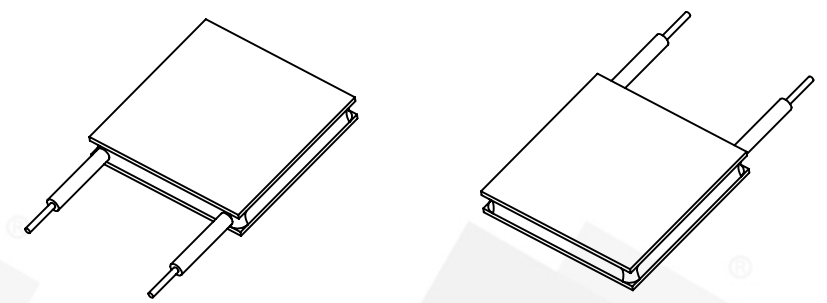
TEC 1 - 017 XX 23 23

热致冷组件 陶瓷结构式 级数 电堆数 最大电流 外形尺寸(A) 外形尺寸(B)

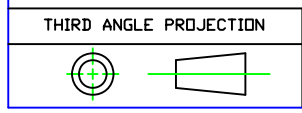
注意事项:

1. 半导体致冷片总成厚度公差为 ± 0.2 , 客户在和散热片组装时, 需要考量此公差带, 不得压得太紧, 也不能压得太松, 否则会导致半导体致冷片破裂或降低功效。
2. 半导体致冷片在通电前, 检查是否有安装符合要求当量的散热片, 禁止空载, 否则会因工作所产生热源没有传递走而烧坏。
3. 标准的半导体致冷片型号及规格参数如下列表 (如有更改, 不另行通知, 非标规格需要定制, 请联络销售部):

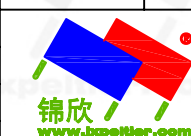
序号 ITEM	型号 PART NUMBER	电堆数 COUPLES	最大电流 A (MAX)	最大电压 V (MAX)	最大冷量(W) 室温环境TH=27°	最大温差(°C)	外形尺寸(MM)			电阻 Ω	重量 g
							A	B	H 实物为准		
1	TEC1-017092323	017	9	2	10.1	66	23	23	5.3	--	--
2	TEC1-017302323		30		34	66	23	23	4.4	--	--



*DO NOT SCALE DRAWING



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1. UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE MM 2. TOLERANCE ARE AS FOLLOWS: 0 < X < 2 ± 0.06 2 < X < 10 ± 0.08 10 < X < 50 ± 0.12 50 < X < 100 ± 0.16 100 < X < 200 ± 0.20 200 < X < 300 ± 0.30 ANGLES ± 0.5°	Part NO.	TEC1-017xx2323	DESCRIPTION	DC 2V(Max), 9~30A, 017晶堆, 单层, 冷端23x23, 热端23x23mm		
	SIGNATURE		DATE		 锦欣制冷(苏州)有限公司 JXPELTIER (SUZHOU) CO., LTD Tel/Fax: +86-512-62539286 Mobile: +86-18061938176 emailto: jxpeltier@gmail.com http://www.jxpeltier.com	
	DRAWN BY	GARY	2008/03/12			
	CHECKED BY	JACK	2008/03/12			
	ENGR	VIVI	2008/03/12			
APPROVED BY	JASON	2008/03/12				
MATERIAL:	ISSUED BY	LILY	2008/03/12	CAD DWG:	SCALE: 1:1	REV: A
				CAD DWG:	SIZE: A3	SHEET: 1 OF 1